

NE5550279A

Silicon Power LDMOS FET

R09DS0033EJ0100 Rev.1.00 Mar 28, 2012

FEATURES

High Output Power
 P_{out} = 33.0 dBm TYP. (V_{DS} = 7.5 V, I_{Dset} = 40 mA, f = 460 MHz, P_{in} = 15 dBm)
 High power added efficiency
 η_{add} = 68% TYP. (V_{DS} = 7.5 V, I_{Dset} = 40 mA, f = 460 MHz, P_{in} = 15 dBm)
 G_L = 22.5 dB TYP. (V_{DS} = 7.5 V, I_{Dset} = 40 mA, f = 460 MHz, P_{in} = 0 dBm)

• High ESD tolerance

• Suitable for VHF to UHF-BAND Class-AB power amplifier.

APPLICATIONS

• 150 MHz Band Radio System

• 460 MHz Band Radio System

• 900 MHz Band Radio System

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
NE5550279A	NE5550279A-A	79A	W7	12 mm wide embossed taping
		(Pb Free)		Gate pin faces the perforation side of the tape
NE5550279A-T1	NE5550279A-T1-A	-		12 mm wide embossed taping
				Gate pin faces the perforation side of the tape
				Qty 1 kpcs/reel
NE5550279A-T1A	NE5550279A-T1A-A			12 mm wide embossed taping
				Gate pin faces the perforation side of the tape
				Qty 5 kpcs/reel

Remark To order evaluation samples, please contact your nearby sales office.

Part number for sample order: NE5550279A

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$, unless otherwise specified)

Operation in excess of any one of these parameters may result in permanent damage.

Parameter	Symbol	Ratings	Unit
Drain to Source Voltage	V_{DS}	30	V
Gate to Source Voltage	V_{GS}	6.0	V
Drain Current	I _{DS}	0.6	Α
Drain Current	I _{DS-pulse}	1.2	Α
(50% Duty Pulsed)			
Total Power Dissipation Note	P _{tot}	6.25	W
Channel Temperature	T _{ch}	150	°C
Storage Temperature	T _{stg}	–55 to +150	°C

Note: Value at $T_C = 25^{\circ}C$

CAUTION

Observe precautions when handling because these devices are sensitive to electrostatic discharge.

RECOMMENDED OPERATING RANGE ($T_A = 25$ °C)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Drain to Source Voltage	V_{DS}		_	7.5	9.0	V
Gate to Source Voltage	V_{GS}		1.65	2.20	2.85	V
Drain Current	I _{DS}		_	0.4	-	Α
Input Power	Pin	f = 460 MHz, V _{DS} = 7.5 V	_	15	20	dBm

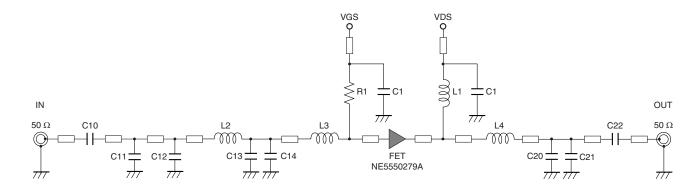
ELECTRICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
DC Characteristics						
Gate to Source Leakage Current	I_{GSS}	V _{GS} = 6.0 V	-	-	100	nA
Drain to Source Leakage Current	I_{DSS}	V _{DS} = 25 V	_	_	10	μΑ
(Zero Gate Voltage Drain Current)						
Gate Threshold Voltage	V_{th}	$V_{DS} = 7.5 \text{ V}, I_{DS} = 1.0 \text{ mA}$	1.15	1.65	2.25	V
Drain to Source Breakdown Voltage	BV _{DSS}	I _{DS} = 10 μA	25	38	-	V
Transconductance	G _m	$V_{DS} = 7.5 \text{ V}, I_{DS} = 100\pm100 \text{ mA}$	1.8	2.2	2.9	S
Thermal Resistance	R _{th}	Channel to Case	_	20.0	-	°C/W
RF Characteristics						
Output Power	P _{out}	f = 460 MHz, V _{DS} = 7.5 V,	31.5	33.0	_	dBm
Drain Current	I _{DS}	P _{in} = 15 dBm,	_	0.38	-	Α
Power Drain Efficiency	$\eta_{\sf d}$	I _{Dset} = 40 mA (RF OFF)	_	70	-	%
Power Added Efficiency	η_{add}		-	68	-	%
Linear Gain	G_L^{Note}		-	22.5	-	dB

Note: $P_{in} = 0 dBm$

Remark DC performance is 100% testing. RF performance is testing several samples per wafer. Wafer rejection criteria for standard devices is 1 reject for several samples.

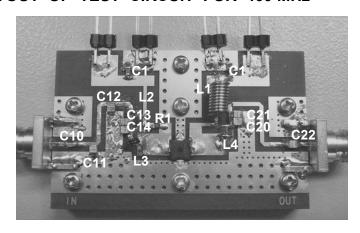
TEST CIRCUIT SCHEMATIC FOR 460 MHz



COMPONENTS OF TEST CIRCUIT FOR MEASURING ELECTRICAL CHARACTERISTICS

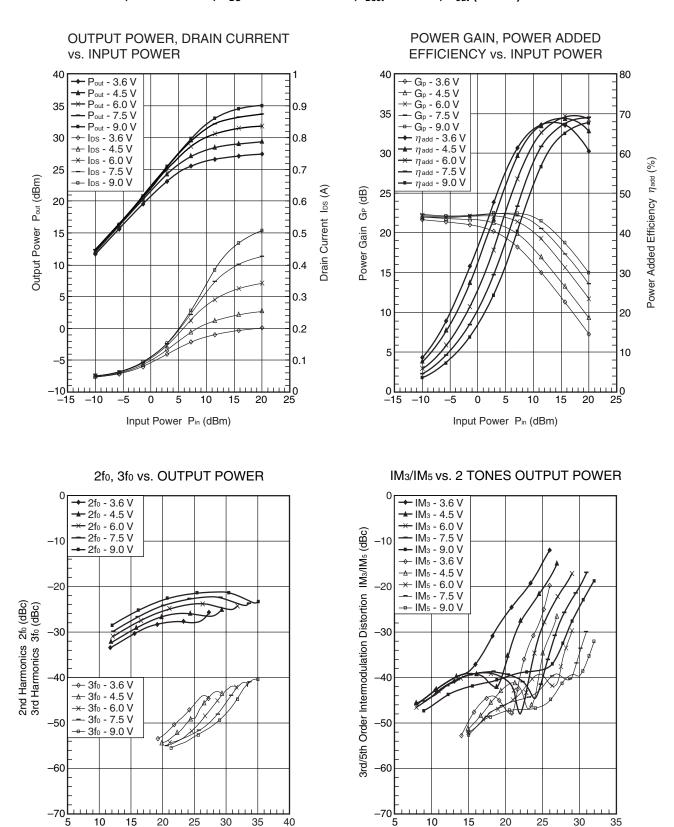
Symbol	Value	Туре	Maker
C1	1 <i>μ</i> F	GRM188B31C105KA92	Murata
C10	22 pF	GRM1882C1H220JA01	Murata
C11	1.2 pF	ATC100A1R2JW	American Technical Ceramics
C12	4.7 pF	ATC100A4R7BW	American Technical Ceramics
C13	15 pF	ATC100A150BW	American Technical Ceramics
C14	12 pF	ATC100A120BW	American Technical Ceramics
C20	10 pF	ATC100A100JW	American Technical Ceramics
C21	3.9 pF	ATC100A3R9BW	American Technical Ceramics
C22	100 pF	ATC100A101JW	American Technical Ceramics
R1	2 kΩ	1/10 W Chip Resistor RK73B1JTTD202J	KOA
L1	123 nH	ϕ 0.5 mm, ϕ D = 3 mm, 10 Turns	Ohesangyou
L2	10 nH	LQW18AN10NG00	Murata
L3	9.8 nH	ϕ 0.4 mm, ϕ D = 1.6 mm, 3 Turns	Ohesangyou
L4	20 nH	ϕ 0.5 mm, ϕ D = 3 mm, 2 Turns	Ohesangyou
PCB	_	R4775, t = 0.4 mm, ε r = 4.5, size = 30 × 48 mm	Panasonic
SMA Connecter	_	WAKA 01K0790-20	WAKA

COMPONENT LAYOUT OF TEST CIRCUIT FOR 460 MHz



TYPICAL CHARACTERISTICS 1 ($T_A = 25^{\circ}C$)

R: f = 460 MHz, $V_{DS} = 3.6/4.5/6/7.5/9$ V, $I_{Dset} = 40$ mA, $P_{in} = -10$ to 20 dBm IM: f1 = 460 MHz, f2 = 461 MHz, $V_{DS} = 3.6/4.5/6/7.5/9$ V, $I_{Dset} = 40$ mA, P_{out} (2 tone) = 8 to 32 dBm



Remark The graphs indicate nominal characteristics.

Output Power Pout (dBm)

2 Tones Output Power Pout (2 tone) (dBm)

S-PARAMETERS

S-parameters and noise parameters are provided on our Web site in a format (S2P) that enables the direct import of the parameters to microwave circuit simulators without the need for keyboard inputs.

Click here to download S-parameters.

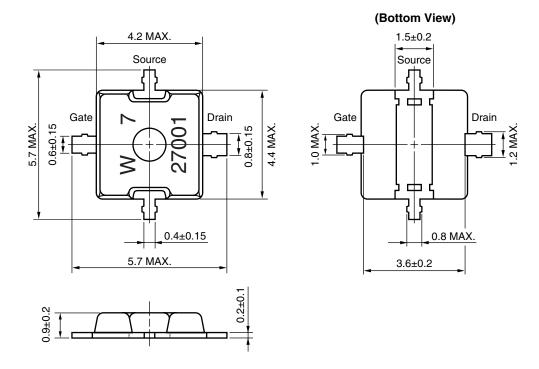
 $[RF\ Devices] \rightarrow [Design\ Support] \rightarrow [Development\ Data\ Download]$

URL http://www.renesas.com/products/microwave/download/index.jsp

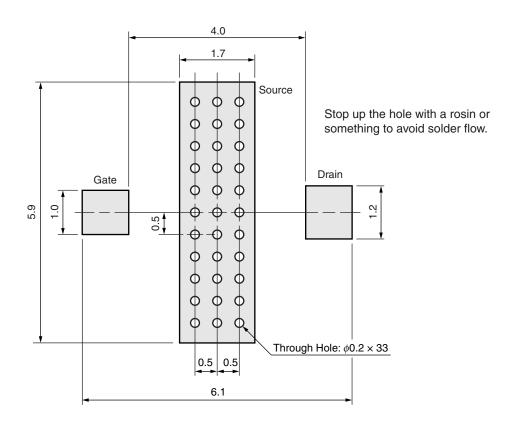


PACKAGE DIMENSIONS

79A (UNIT: mm)



79A PACKAGE RECOMMENDED P.C.B. LAYOUT (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature)	: 260°C or below	IR260
	Time at peak temperature	: 10 seconds or less	
	Time at temperature of 220°C or higher	: 60 seconds or less	
	Preheating time at 120 to 180°C	: 120±30 seconds	
	Maximum number of reflow processes	: 3 times	
	Maximum chlorine content of rosin flux (% mass)	: 0.2% (Wt.) or below	
Wave Soldering	Peak temperature (molten solder temperature)	: 260°C or below	WS260
	Time at peak temperature	: 10 seconds or less	
	Preheating temperature (package surface temperature)		
		: 120°C or below	
	Maximum number of flow processes	: 1 time	
	Maximum chlorine content of rosin flux (% mass)	: 0.2% (Wt.) or below	
Partial Heating	Peak temperature (terminal temperature)	: 350°C or below	HS350
	Soldering time (per side of device)	: 3 seconds or less	
	Maximum chlorine content of rosin flux (% mass)	: 0.2% (Wt.) or below	

CAUTION

Do not use different soldering methods together (except for partial heating).

Revision History

NE5550279A Data Sheet

		Description		
Rev.	Date	Page	Summary	
1.00	Mar 28, 2012	-	First edition issued	

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